

# HFB20HJ20C

PD-94169B

Ultrafast, Soft Recovery Diode Surface Mount (SMD-0.5) 200V, 20A

#### **Features**

- Reduced RFI and EMI
- Reduced snubbing
- Extensive characterization of recovery parameters
- Hermetic package
- Surface mount

#### **Potential Applications**

- DC-DC converter
- Motor drives

#### **Product Validation**

Qualified according to MIL-PRF-19500 for space applications

# SMD-0.5

**Product Summary** 

**V<sub>R</sub>: 200V** 

**V**<sub>F:</sub> 1.3V

**t**<sub>rr</sub>: 40ns

#### **Description**

HFB20HJ20C is part of the IR HiRel family of products. These Ultrafast, soft recovery diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motor drives and other applications where switching losses are significant portion of the total losses.

# **Ordering Information**

Table 1 Ordering options

•	•	
Part number	Package	Screening Level
HFB20HJ20C	SMD-0.5	COTS
HFB20HJ20CSCV	SMD-0.5	JANTXV-equivalent
HFB20HJ20CSCX	SMD-0.5	JANTX-equivalent
HFB20HJ20CSCS	SMD-0.5	S-level

# HFB20HJ20C

# FRED Ultrafast, Soft Recovery Diode



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**Absolute Maximum Ratings** 

# 1 Absolute Maximum Ratings

Table 2 Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_R$	Cathode to anode voltage (Per Leg)	200	V
I <sub>F(AV)</sub>	Continuous forward current, T <sub>C</sub> = 85°C <sup>1</sup>	20	Α
I <sub>FSM</sub>	Single pulse forward current, T <sub>c</sub> = 25°C <sup>2</sup> (Per Leg)	125	Α
$P_D @ T_C = 25^{\circ}C$	Maximum power dissipation	28	W
T <sub>J</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 to 150	°C
Wt	Weight	1.0 (Typical)	g

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<sup>&</sup>lt;sup>1</sup> DC = 50% rectangle wave

 $<sup>^2</sup>$  ½ sine wave, 60 Hz, Pulse width = 8.33 ms



**Device Characteristics** 

#### 2 Device Characteristics

#### 2.1 Electrical Characteristics

Table 3 Electrical Characteristics (Per Leg) @ T<sub>J</sub> = 25°C (unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions
$V_{BR}$	Cathode Anode Breakdown Voltage	200	_	_	V	$I_R = 100 \mu A$
		_	_	1.26	V	I <sub>F</sub> = 10A, T <sub>J</sub> = -55°C
V	Max Forward Voltage Drop See Fig. 1	_	_	1.11	V	$I_F = 10A, T_J = 25^{\circ}C$
$V_{F}$		_	_	1.30	V	$I_F = 20A, T_J = 25^{\circ}C$
		_	_	0.96	V	I <sub>F</sub> = 10A, T <sub>J</sub> = 125°C
	Max Reverse Leakage Current	_	_	10	μΑ	$V_R = V_R$ Rated
$I_R$	See Fig. 2	_	_	1.0	mA	V <sub>R</sub> = 960V, T <sub>J</sub> = 125°C
Cı	Junction Capacitance See Fig. 3	_	_	41	pF	V <sub>R</sub> = 200V
Ls	Series Inductance	_	4.8	_	nH	Measured from center of cathode pad to center of anode pad

# 2.2 Dynamic Recovery Characteristics

Table 4 Dynamic Recovery Characteristics (Per Leg) @ T<sub>J</sub> =25°C (unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Мах.	Unit	<b>Test Condition</b>	S
t <sub>rr</sub>	Reverse Recovery Time	_	_	40	ns	T <sub>J</sub> = 25°C	1 - 204
I <sub>RRM1</sub>	Peak Recovery Current	_	3.5	_		T <sub>J</sub> = 25°C	I <sub>F</sub> = 20A
I <sub>RRM2</sub>	See Fig. 6	_	5.5	_	<b>A</b>	T <sub>J</sub> = 125°C	V <sub>R</sub> = 160V
Q <sub>rr1</sub>	Reverse Recovery Charge	_	54	_		T <sub>J</sub> = 25°C	
Q <sub>rr2</sub>	See Fig. 7	_	120	_	nC	T <sub>J</sub> = 125°C	$d_{if}/dt = 200 A/ \mu s$
$\overline{di_{(rec)M}/dt_1}$	Peak Rate of Fall of Recovery	_	640	_		T <sub>J</sub> = 25°C	
$di_{(rec)M}/dt_2$	Current During t₀ See Fig. 8	_	850	_	A/ μs	T <sub>J</sub> = 125°C	

#### 2.3 Thermal-Mechanical Characteristics

Table 5 Thermal-Mechanical Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}$	Junction to Case, Single Leg Conducting		4.5	°C/W



**Electrical Characteristics Curves** 

#### 3 Electrical Characteristics Curves

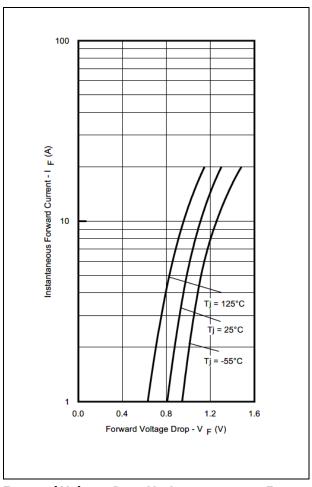


Figure 1 Typical Forward Voltage Drop Vs. Instantaneous Forward Current (Per Leg)

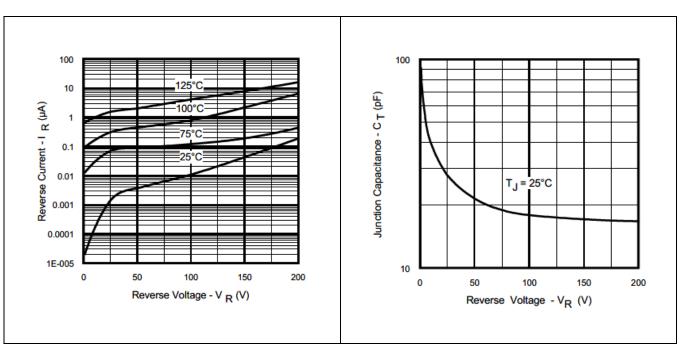


Figure 2 Typical Values of Reverse Current Vs. Reverse Voltage (Per Leg)

Figure 3

Typical Junction Capacitance Vs. Reverse Voltage (Per Leg)

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#### **Electrical Characteristics Curves**

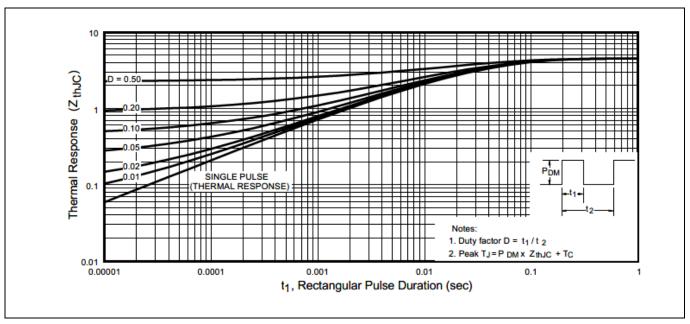


Figure 4 Maximum Thermal Impedance Z<sub>thJc</sub> Characteristics (Per Leg)

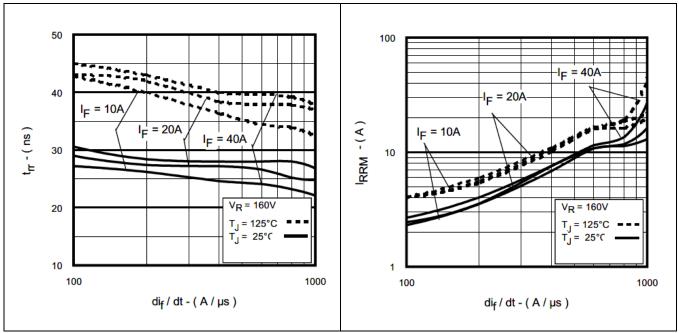


Figure 5 Typical Reverse Recovery Vs. di<sub>f</sub>/dt (Per Leg)

Figure 6 Typical Recovery Current Vs. di<sub>f</sub>/dt (Per Leg)



#### **Electrical Characteristics Curves**

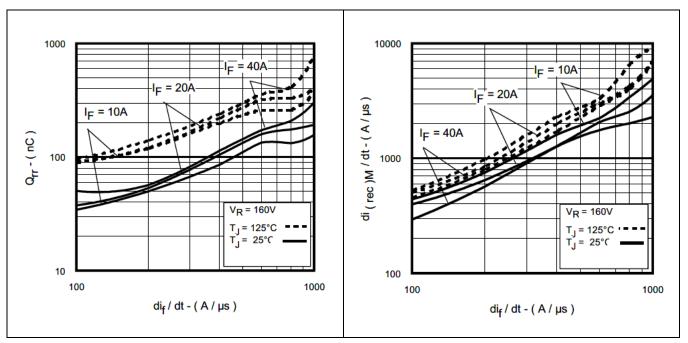


Figure 7 Typical Stored Charge Vs. di<sub>f</sub>/dt (Per Leg)

 $Figure \ 8 \qquad Typical \ di_{(rec)M}/dt \ Vs. \ di_f/dt \ (Per \ Leg)$ 



**Test Circuit** 

#### 4 Test Circuit

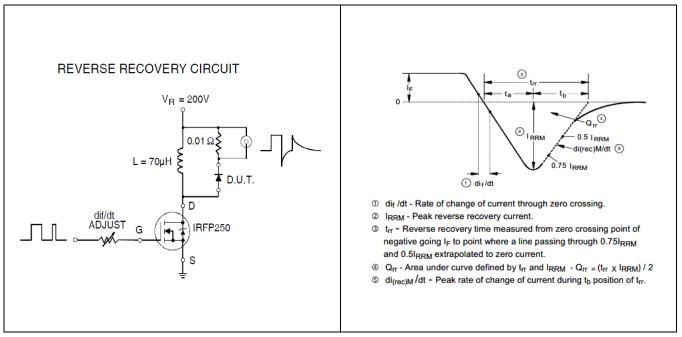


Figure 9 Reverse Recovery Parameter Test Circuit

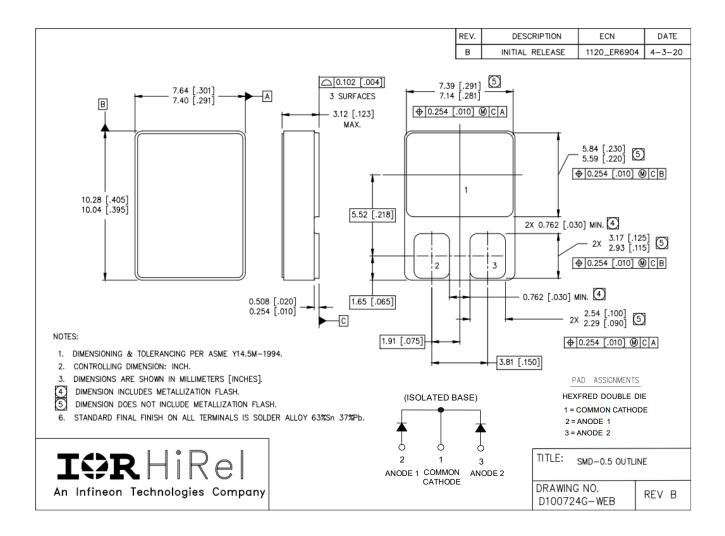
Figure 10 Reverse Recovery Waveform and Definitions



**Package Outline** 

# 5 Package Outline

Note: For the most updated package outline, please see the website: **SMD-0.5** 



# HFB20HJ20C

# FRED Ultrafast, Soft Recovery Diode



**Revision history** 

# **Revision history**

Document version	Date of release	Description of changes
	04/30/1998	Final datasheet (PD-94169)
Rev A	05/08/2001	Updated per ECN-1120-03627
Rev B	10/06/2025	Updated per ECN-Z8F80840776

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